

PNP Transistor Bare Die - 2N4209A

Rev 1.1 08/03/19

Ultra-high speed Saturated Switch in bare die form

Complement NPN 2N2369A

Features:

- Higher 20V breakdown voltage versus 2N4209
- Very fast t_{on} + t_{off} switching time + low capacitance
- Collector current up to 200mA
- High Reliability Gold Back Metal
- High Reliability tested grades for Military + Space

Ordering Information:

The following part suffixes apply:

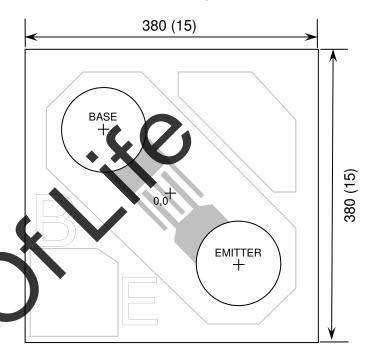
- No suffix MIL-STD-750 /2072 Visual Inspection
- "H" MIL-STD-750 /2072 Visual Inspection+ MIL-PRF-38534 Class B. AT
- "K" MIL-STD-750 /2072 Visual Inspection+ MIL-PRF-38534 Class K LAT

LAT = Lot Acceptance Test,

For further information on LAN process flows see below.

www.siliconsupplies.com\quality\bare-die-lot-qualification

Die Dimensions in μm (mils)



PAD	COORDINATES (µm)				
	X	Υ			
BASE	-70	70			
EMITTER	70	-70			
CHIP BACKSIDE IS COLLECTOR					

Supply Formats:

- Default Die in Waffle Pack (400 per tray capacity)
- Sawn Wafer on Tape Specific request
- Unsawn Wafer Specific request
- With additional electrical selection Specific request
- Sawn as pairs or adjacent pair pick Specific request

Mechanical Specification

Die Size (Unsawn)	380 x 380 15 x 15	μm mils	
Base Pad Size Emitter Pad Size	110 Ø 4.33 Ø	μm mils	
Die Thickness	200 (±20) 7.87 (±0.79)	μm mils	
Top Metal Composition	Al 1.3μm		
Back Metal Composition	Au 1.7μm		





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Absolute Maximum Ratings T_A = 25°C unless otherwise stated

PARAMETER	SYMBOL	VALUE	UNIT
Collector-Base Voltage	V_{CBO}	-20	V
Collector-Emitter Voltage	V _{CEO}	-20	V
Emitter-Base Voltage	V_{EBO}	-4.5	V
Collector Current	Ic	200	mA
Junction & Storage Temperature	T _J , T _{stg}	-55 to 200	°C

Electrical Characteristics T_A = 25°C unless otherwise stated

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	V _{(BR)CBO}	$I_{C} = 100 \mu A, I_{A} = 0$	-20	-	-	V
Collector-Emitter Breakdown Voltage	$V_{(BR)CEO}$	$I_C = 3mA$, $I_B = 0$	-20	-	-	V
Collector-Emitter Breakdown Voltage	V _{(BR)CES}	$I_{C} = 100 \mu A, V_{BE} = 0$	-20	-	-	V
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	$I_{E} = 100 \mu A, I_{C} = 0$	4.5	-	-	V
Collector Cut-off Current ¹		CE = -8V, VBE = 0	-	-	10	nA
Collector Gut-on Gurrent	I _{CES}	V _{CE} = -8V, V _{BE} = 0, T _A = 125°C	-	-	5	μΑ
ON CHARACTERISTICS						
Forward-Current Transfer Ratio ¹		$V_{CE} = -0.5V$, $I_{C} = 1 \text{mA}$	35	-	-	-
	h _{FE}	V _{CE} -0.3V, I _C = 10mA	50	-	120	-
	IIFE	$V_{CE} = -0.3V$, $I_C = 10mA$, $T_A = -55^{\circ}C$	20	-	-	-
		$V_{CE} = -1V, I_{C} = 50mA$	40			
Collector-Emitter Saturation Voltage		$I_{C} = 1 \text{mA}, I_{B} = 0.1 \text{mA}$		-	-0.15	V
Pulsed Collector-Emitter Saturation	Voe(sat)	$I_C = 10\text{mA}, I_B = 1\text{mA}$	-	-	-0.18	V
Voltage ¹		$I_{C} = 50 \text{mA}, I_{B} = 5 \text{mA}$	-	-	-0.6	V
Base-Emitter Saturation Voltage		$I_C = 1 \text{mA}, I_B = 0.1 \text{mA}$	-	-	-0.8	V
Pulsed Base-Emitter Saturation	VBE(sat)	$I_C = 10$ mA, $I_B = 1$ mA	-0.8	-	-0.95	V
Voltage ¹		$I_C = 50$ mA, $I_B = 5$ mA	-	-	-1.5	V
SMALL SIGNAL CHARACTERISTICS						
High Frequency Current Gain	h _{fe}	$I_C = 10mA, V_{CE} = -10V,$ f = 100MHz	-	-	8.5	-
Output Capacitance	C _{ob}	$V_{CB} = -5V, I_{E} = 0$	-	-	3	pF
Input Capacitance	C _{ib}	$V_{BE} = -0.5V, I_{C} = 0$	-	-	3.5	
SWITCHING CHARACTERISTICS ²						
Transition Frequency	f _T	$V_{CE} = -10V$, $I_C = 10mA$, $f = 100MHz$	850	-	-	MHz
Turn-On Time	ton	$I_C = 10mA$, $I_{B1} = 1mA$, $V_{CC} = -1.5V$	-	-	15	ns
Turn-Off Time	t _{off}	$I_C = 10mA$, $I_{B1} = I_{B2} = 1mA$, $V_{CC} = -1.5V$	-	-	20	
Storage Time	ts	$I_C = 10mA$, $I_{B1} = I_{B2} = 10mA$, $V_{CC} = -3V$	-	-	20	

Note 1: Pulse conditions : length = $300\mu s$; duty cycle = 1%

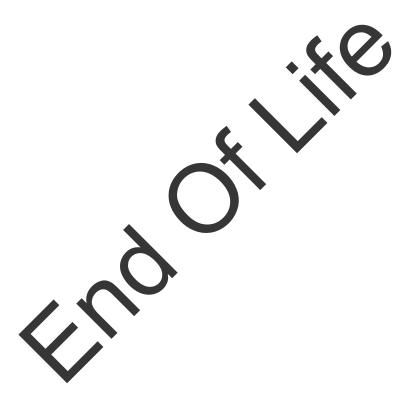
Note 2: Not production testing in die form, proven by chip design and qualification test





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